

## Specifications

### 1. Material

6061-T6 or equivalent Al core  
Total Thickness: 0.040" (1.016 mm)  
Dielectric Thickness: 0.003"  
Layer 1 – Top Layer, 2 oz copper

### 2. Hole Plating

N/A

### 3. Finish

A: Electroless Nickel/Immersion Gold (ENIG)

#### B: Solder Mask

Liquid Photo Image (LPI)

Electra LPI-White

or Approved Equal

Solder Mask Over Bare Copper (SMOBC)

#### C: Silk Screen

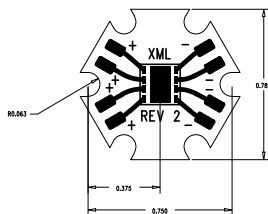
Black Epoxy Ink, Component Side

### 4. Tolerances

Overall board dimension tolerance +/- .010

Hole diameter >.100 +/- .005

Hole diameter <=.100 +/- .005



FAB DRAWING  
TOP SIDE SILKSCREEN

TOP SIDE COPPER